



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2019-01-24
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS1L30U	HNZJ*Z25Q81Q	A	ZA41	2019-01-24
	Amount	UoM	Unit type	ST ECOPACK Grade
	107.00	mg	Each	ECOPACK2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.50X2.16X3.68	1	J BEND	
Comment	Package: SMB CLIP (SOD 6 NEW)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 26th October 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	112
Lead	2.34	Soft solder	21860

QueryList : REACH-15th January 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.34	Soft solder	21860
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.34	Soft solder	925237

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HNZI*Z25Q81Q					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.142	mg	supplier	die	Silicon (Si)	7440-21-3		1.086	mg	951380	10150
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	6132	65
				supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	4380	47
				supplier	passivation	Nickel (Ni)	7440-02-0		0.005	mg	4380	47
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	876	9
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	6132	65
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	877	9
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1752	19
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	6132	65
				supplier	polymer die coating	Durimide	Proprietary		0.021	mg	17959	192
Leadframe & Clip	Copper and its alloy	44.505	mg	Supplier	alloy	Copper (Cu)	7440-50-8		44.484	mg	999528	415738
				Supplier	alloy	Zinc (Zn)	7440-66-6		0.002	mg	45	19
				Supplier	alloy	Iron (Fe)	7439-89-6		0.004	mg	90	37
Die attach	Other organic material	2.528	mg	Supplier	alloy	Iron Phosphide(FeP)	26508-33-8		0.015	mg	337	140
				Supplier	soft solder	Silver (Ag)	7440-22-4		0.063	mg	24921	589
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.126	mg	49842	1178
Encapsulation	Other organic material	57.802	mg	JIG R	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.339	mg	925237	21864
				Supplier	mold compound	silica fused	7631-86-9		42.771	mg	739957	399729
				Supplier	mold compound	silica quartz	14808-60-7		11.560	mg	199993	108037
				Supplier	mold compound	phenolic resin	9003-35-4		2.891	mg	50016	27019
Connection coating	Other inorganic material	1.023	mg	Supplier	mold compound	carbon black	1333-86-4		0.580	mg	10034	5421
				Supplier	solder alloy	Tin (Sn)	7440-31-5		1.023	mg	1000000	9561